



DDR SODIMM, DDR2 SO DIMM

TE Internal #: 1827341-4

SO DIMM Sockets, Double Data Rate (DDR) 2, Stack Height .315 in [8 mm], Right Angle Module Orientation, Surface Mount Mount, DDR SODIMM

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Connectors > Socket Connectors > Memory Sockets > SO DIMM Sockets > DDR2 SO DIMM Sockets



DRAM Type: **Double Data Rate (DDR) 2**

Stack Height: **8 mm [.315 in]**

Module Orientation: **Right Angle**

PCB Mounting Style: **Surface Mount**

Connector System: **Cable-to-Board**

[All DDR2 SO DIMM Sockets \(30\)](#)

Features

Product Type Features

Center Post	Without
DRAM Type	Double Data Rate (DDR) 2
Connector System	Cable-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Product Type	Socket

Configuration Features

Number of Bays	2
Center Key	Offset Left
Number of Keys	1
Module Orientation	Right Angle
Number of Positions	200
Number of Rows	2



Keying	Standard
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Electrical Characteristics

DRAM Voltage	1.8 V
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Signal Characteristics

SGRAM Voltage	1.8 V
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Body Features

Ejector Location	Both Ends
Retention Post Location	Center
Module Key Type	Offset Left
Ejector Type	Locking
Connector Profile	Standard

Contact Features

Socket Style	SO DIMM
Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Gold
Contact Base Material	Copper Alloy
Contact Mating Area Plating Material	Gold
Contact Current Rating (Max)	.5 A
Socket Type	Memory Card

Termination Features

Insertion Style	Cam-In
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Mechanical Attachment

PCB Mount Retention	With
PCB Mount Retention Type	Solder Tail
PCB Mounting Style	Surface Mount
Connector Mounting Type	Board Mount

Housing Features

Centerline (Pitch)	.6 mm [.024 in]
Housing Color	Black
Housing Material	LCP (Liquid Crystal Polymer)

Dimensions

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Stack Height	8 mm[.315 in]
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Row-to-Row Spacing	6.2 mm[.244 in]
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Usage Conditions

Operating Temperature Range	-55 – 85 °C[-67 – 185 °F]
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Operation/Application

Circuit Application	Power
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Industry Standards

UL Flammability Rating	UL 94V-0
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Packaging Features

Packaging Method	Box, Tray
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Packaging Quantity	20
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Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
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EU ELV Directive 2000/53/EC	Compliant
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China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
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EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JAN 2022 (223) SVHC > Threshold: Not Yet Reviewed
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Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
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Solder Process Capability	Reflow solder capable to 260°C
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Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



TE Part # 2309407-1
DDR4 SODIMM 260P 4.0H STD

Also in the Series | DDR SODIMM



SO DIMM Sockets(7)

Also in the Series | DDR2 SO DIMM



SO DIMM Sockets(24)

Customers Also Bought



TE Part #4515DO-DS3BK005DP
5IN PCB MOUNT I2C DIFF PRESSURE SENSOR



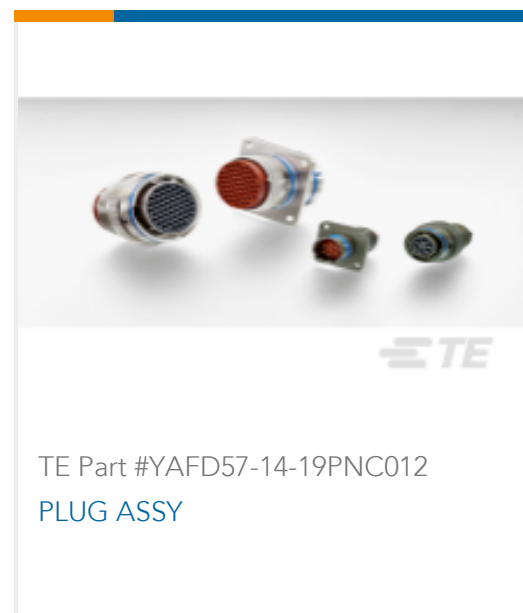
TE Part #1-1623732-0
BCHE 7 W 180R 5%



TE Part #3-794619-8
08P MICRO MNL ASSY,R/A,HDR LF



TE Part #5-1734857-5
PCI EXP STRADDLE 36P BLK 30u"



Documents

Product Drawings

DDR SODIMM SOCKET 200P 8H STD TYPE

English

CAD Files

Customer View Model

[ENG_CVM_CVM_1827341-4_G1.2d_dxf.zip](#)

English

3D PDF

3D

Customer View Model

[ENG_CVM_CVM_1827341-4_G1.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_1827341-4_G1.3d_stp.zip](#)

English

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Product Specifications

Product Specification

English

Product Environmental Compliance

[MD_1827341-4_12112017724_dmtec](#)

English

[MD_1827341-4_12112017724_dmtec](#)

English

